

# PATENT ABSTRACTS OF JAPAN

(11) Publication number : **10-163591**

(43) Date of publication of application : **19.06.1998**

(51) Int.Cl.

H05K 1/11

(21) Application number : **08-320508**

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(22) Date of filing : **29.11.1996**

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## (54) PRINTED CIRCUIT BOARD

### (57) Abstract:

**PROBLEM TO BE SOLVED:** To improve connecting reliability and yield of a through-hole connection by constituting plated the through-hole by a plurality of through-holes formed continuously along a predetermined straight line.

**SOLUTION:** According to the printed circuit board 10, a through-hole connecting terminal 18 is constituted by cutting a plated through hole 20, formed by a plurality of through holes 20a to 20c continuously disposed on a straight line A along a predetermined cutting line B. Thus, even if the line B deviates slightly due to a processing error, a through-hole connecting terminal 18 having an opening width of at least single through-hole of a diameter or more can be obtained. Accordingly, the terminal 18 having sufficient opening area is constituted at the time of connecting solder fillet 30 can be smoothly formed. As a result, the board 10 having high connecting reliability and improved connecting yield can be obtained.

